8223A-SR

Wi-Fi Dual-band 1X1 11ac + Bluetooth 5.0

Combo Module Datasheet

8223A-SR Module Datasheet

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Customer Approval :

_____ Company

_____ Title

_____ Signature

_____ Date

_____ Fn-Link

Revision History

Version	Date	Revision Content	Draft	Approved
1.0	2018/11/09	New version	Lzm	Jacky
1.1	2018/12/18	Modify the telephone number	Lzm	Lxy
1.2	2018/12/25	Modify the office and TEL	Lzm	Lxy
1.3	2019/01/08	Add Carrier Tape Detail	Lzm	WDD
1.4	2021/05/28	Add chip information	Lxy	Szs
1.5	2021/09/15	Update package quanlity	Lxy	QJP

CONTENTS

1 Overview

1.1 Introduction

Fn-Link Technology would like to announce a low-cost and low-power consumption module which has all of the Wi-Fi, Bluetooth functionalities. The highly integrated module makes the possibilities of web browsing, VoIP, Bluetooth headsets applications. With seamless roaming capabilities and advanced security, also could interact with different vendors' 802.11a/b/g/n/ac Access Points in the wireless LAN.

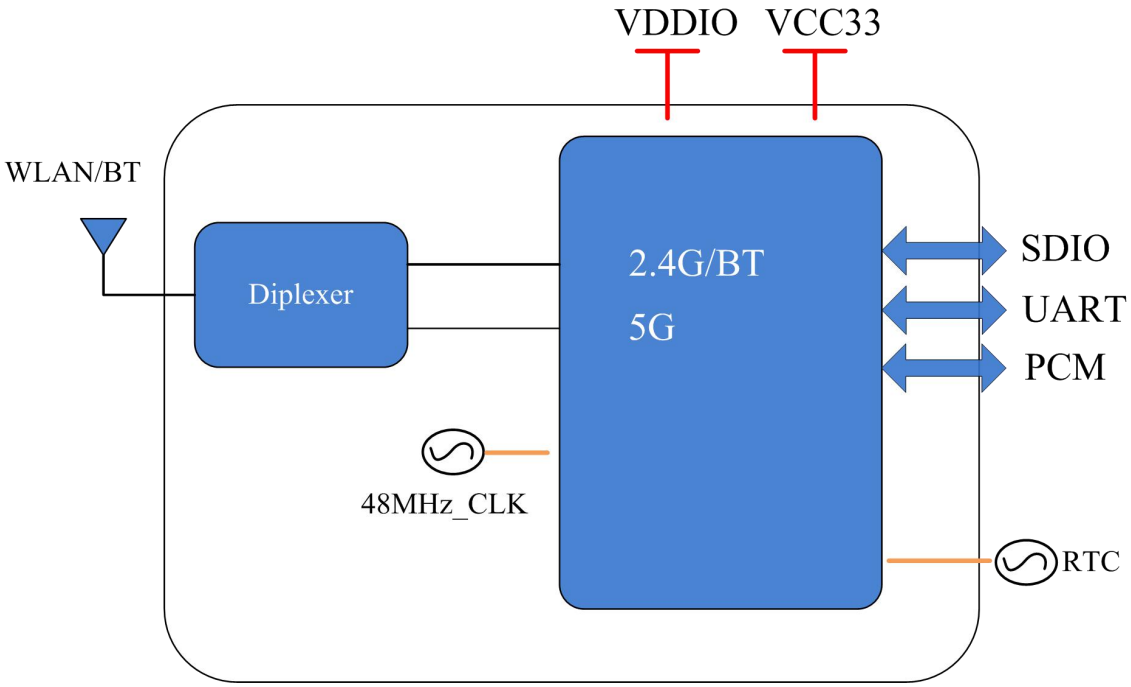
The wireless module complies with IEEE 802.11 a/b/g/n/ac standard and it can achieve up to a speed of 433.3Mbps with single stream in 802.11ac draft to connect to the wireless LAN. The integrated module provides SDIO interface for Wi-Fi, UART / PCM interface for Bluetooth.

This compact module is a total solution for a combination of Wi-Fi + BT technologies. The module is specifically developed for Smart phones and Portable devices.

1.2 Features

- Highly integrated wireless local area network(WLAN) system-on-chip (SOC) for 5 GHZ 802.11ac, or 2.4G/5G 802.11n WLAN applications.
- Supports 20/40MHz at 2.4GHz and supports 20/40/80MHz at 5GHz
- Supports low power SDIO3.0 interface for WLAN and UART/PCM interface for Bluetooth.
- Supports Bluetooth V5.0, BLE and be backwards compatible with Bluetooth 1.2, 2.X+ enhance data rate.
- Supports WLAN-Bluetooth coexistence.
- Supports Bluetooth for class1 and class2 power level transmissions without requiring an external PA.
- BT host digital interface:
    - HCI UART (up to 4 Mbps)
    - PCM for audio data

Block Diagram:



1.3 General Specification

Model Name	8223A-SR
Product Description	Support Wi-Fi/Bluetooth functionalities
Dimension	L x W x H: 12 x 12 x 1.7mm (typical)
Wi-Fi Interface	Support SDIO V3.0
BT Interface	UART / PCM
Operating temperature[1]	-40°C to 85°C
Storage temperature	-40°C to 125°C
RoHS	All hardware components are fully compliant with EU RoHS directive

1.-40 to 70° C range,the module is IEEE compliant.-40 to 85° C range，the module remians the ability for data transimission. Some parameters might degrate or exceed the specifications. When the temperature remains to normal levels, the module will meet IEEE specifications again.

1.4 Recommended Operating Rating

The digital IO supports VDD33 or VDD18 application.

		Min.	Typ.	Max.	Unit
Operating Temperature		-30	25	75	deg.C
VCC33		3.15	3.3	3.45	V
VDDIO		1.7	1.8 or 3.3	3.45	V
Power Consumption		VCC33 = 3.3V(Unit:mA)			
	Wi-Fi on Mode	72			
	TX (2.4G HT20)	220			
	RX (2.4G HT20)	78			
	TX (5G HT80)	220			
	RX (5G HT80)	112			
	BT on	20			

※1.5 EEPROM Information

WI-FI

Vendor ID	0271
Product ID	0701

2 Wi-Fi RF Specification

2.1 2.4GHz RF Specification

Feature	Description
WLAN Standard	IEEE 802.11b/g/n, Wi-Fi compliant
Frequency Range	2.400 GHz ~ 2.497 GHz (2.4 GHz ISM Band)
Number of Channels	2.4GHz：Ch1 ~ Ch14
Output Power	802.11b /11M: 16 dBm ± 1.5 dB EVM ≤ -9dB
	802.11g /54M: 15 dBm ± 1.5 dB EVM ≤ -25dB

	802.11n /MCS7: 14 dBm ± 1.5 dB EVM ≤ -28dB			
Spectrum Mask	Min. b/g/n	Typ. b/g/n	Max. b/g/n	Unit b/g/n
1st side lobes(to fc ± 11MHZ)	-	-42/-30/-40	-	dBr
2st side lobes(to fc ± 22MHZ)	-	-53/-33/-58	-	dBr
Freq. Tolerance	-20/-20/-20	-	20/20/20	ppm

Test Items	**Test Value**		**Standard Value**
Receive Sensitivity (11b) @8% PER	- 1Mbps	PER @ -96 dBm	≤-83
	- 2Mbps	PER @ -90 dBm	≤-80
	- 5.5Mbps	PER @ -88 dBm	≤-79
	- 11Mbps	PER @ -87 dBm	≤-76
Receive Sensitivity (11g) @10% PER	- 6Mbps	PER @ -90 dBm	≤-85
	- 9Mbps	PER @ -88 dBm	≤-84
	- 12Mbps	PER @ -87 dBm	≤-82
	- 18Mbps	PER @ -85 dBm	≤-80
	- 24Mbps	PER @ -83 dBm	≤-77
	- 36Mbps	PER @ -80 dBm	≤-73
	- 48Mbps	PER @ -76 dBm	≤-69
	- 54Mbps	PER @ -74 dBm	≤-68
Receive Sensitivity (11n,20MHz) @10% PER	- MCS=0	PER @ -89 dBm	≤-85
	- MCS=1	PER @ -85 dBm	≤-82
	- MCS=2	PER @ -84 dBm	≤-80
	- MCS=3	PER @ -80 dBm	≤-77
	- MCS=4	PER @ -77 dBm	≤-73
	- MCS=5	PER @ -75 dBm	≤-69
	- MCS=6	PER @ -72 dBm	≤-68
	- MCS=7	PER @ -71 dBm	≤-67
Receive Sensitivity (11n,40MHz) @10% PER	- MCS=0	PER @ -89 dBm	≤-82
	- MCS=1	PER @ -85 dBm	≤-79
	- MCS=2	PER @ -84 dBm	≤-77
	- MCS=3	PER @ -80 dBm	≤-74
	- MCS=4	PER @ -76 dBm	≤-70
	- MCS=5	PER @ -72 dBm	≤-66
	- MCS=6	PER @ -70 dBm	≤-65
	- MCS=7	PER @ -69 dBm	≤-64

2.2 5GHz RF Specification

Feature	Description	
WLAN Standard	IEEE 802.11a/n/ac, Wi-Fi compliant	
Frequency Range	4.900 GHz ~ 5.845 GHz (5.0 GHz ISM Band)	
Number of Channels	5.0GHz：Please see the table[1]	
Modulation	802.11a/n : 64-QAM,16-QAM, QPSK, BPSK 802.11ac : 256-QAM, 64-QAM,16-QAM, QPSK, BPSK	
Output Power	802.11a /54M: 12 dBm ± 2 dB EVM ≤ -25dB	
	802.11n /MCS7: 11 dBm ± 2 dB EVM ≤ -28dB	
	802.11ac/MCS8: 10 dBm ± 2 dB EVM ≤ -30dB	
	802.11ac/MCS9: 10 dBm ± 2 dB EVM ≤ -32dB	
Test Items	**Test Value**	**Standard Value**
Receive Sensitivity (11a, 20MHz) @10% PER	- 6Mbps PER @ -91 dBm	≤-85
	- 9Mbps PER @ -89 dBm	≤-84
	- 12Mbps PER @ -88 dBm	≤-82
	- 18Mbps PER @ -86 dBm	≤-80
	- 24Mbps PER @ -82 dBm	≤-77
	- 36Mbps PER @ -79 dBm	≤-73
	- 48Mbps PER @ -74 dBm	≤-69
	- 54Mbps PER @ -73 dBm	≤-68
Receive Sensitivity (11n,20MHz) @10% PER	- MCS=0 PER @ -90 dBm	≤-85
	- MCS=1 PER @ -88 dBm	≤-82
	- MCS=2 PER @ -85 dBm	≤-80
	- MCS=3 PER @ -82 dBm	≤-77
	- MCS=4 PER @ -78 dBm	≤-73
	- MCS=5 PER @ -74 dBm	≤-69
	- MCS=6 PER @ -72 dBm	≤-68
	- MCS=7 PER @ -71 dBm	≤-67
Receive Sensitivity (11n,40MHz) @10% PER	- MCS=0 PER @ -88 dBm	≤-85
	- MCS=1 PER @ -85 dBm	≤-82
	- MCS=2 PER @ -83 dBm	≤-80
	- MCS=3 PER @ -79 dBm	≤-76
	- MCS=4 PER @ -76 dBm	≤-73
	- MCS=5 PER @ -71 dBm	≤-68
	- MCS=6 PER @ -70 dBm	≤-67

	- MCS=7	PER @ -68 dBm	≤-65
Receive Sensitivity (11ac,20MHz) @10% PER	- MCS=0	PER @ -89 dBm	≤-83
	- MCS=1	PER @ -87 dBm	≤-82
	- MCS=2	PER @ -84 dBm	≤-80
	- MCS=3	PER @ -81 dBm	≤-75
	- MCS=4	PER @ -77 dBm	≤-72
	- MCS=5	PER @ -73 dBm	≤-68
	- MCS=6	PER @ -71 dBm	≤-67
	- MCS=7	PER @ -70 dBm	≤-62
	- MCS=8	PER @ -66 dBm	≤-60
Receive Sensitivity (11ac,40MHz) @10% PER	- MCS=0	PER @ -87 dBm	≤-80
	- MCS=1	PER @ -83 dBm	≤-77
	- MCS=2	PER @ -81 dBm	≤-74
	- MCS=3	PER @ -78 dBm	≤-70
	- MCS=4	PER @ -75 dBm	≤-69
	- MCS=5	PER @ -70 dBm	≤-65
	- MCS=6	PER @ -68 dBm	≤-64
	- MCS=7	PER @ -66 dBm	≤-59
	- MCS=8	PER @ -64 dBm	≤-57
	- MCS=9	PER @ -63 dBm	≤-55
Receive Sensitivity (11ac,80MHz) @10% PER	- MCS=0	PER @ -83 dBm	≤-79
	- MCS=1	PER @ -80 dBm	≤-76
	- MCS=2	PER @ -78 dBm	≤-74
	- MCS=3	PER @ -74 dBm	≤-71
	- MCS=4	PER @ -71 dBm	≤-67
	- MCS=5	PER @ -69 dBm	≤-63
	- MCS=6	PER @ -65 dBm	≤-62
	- MCS=7	PER @ -63 dBm	≤-61
	- MCS=8	PER @ -60 dBm	≤-56
	- MCS=9	PER @ -59 dBm	≤-54

[1]5GHz Channel table

Band (GHz)	Operating Channel Numbers	Channel center frequencies(MHz)
5.15GHz~5.25GHz	36	5180
	40	5200
	44	5220
	48	5240

5.25GHz~5.35GHz	52	5260
	56	5280
	60	5300
	64	5320
5.5GHz~5.7GHz	100	5500
	104	5520
	108	5540
	112	5560
	116	5580
	120	5600
	124	5620
	128	5640
	132	5660
	136	5680
	140	5700
5.725GHz~5.825GHz	149	5745
	153	5765
	157	5785
	161	5805
	165	5825

3 Bluetooth Specification

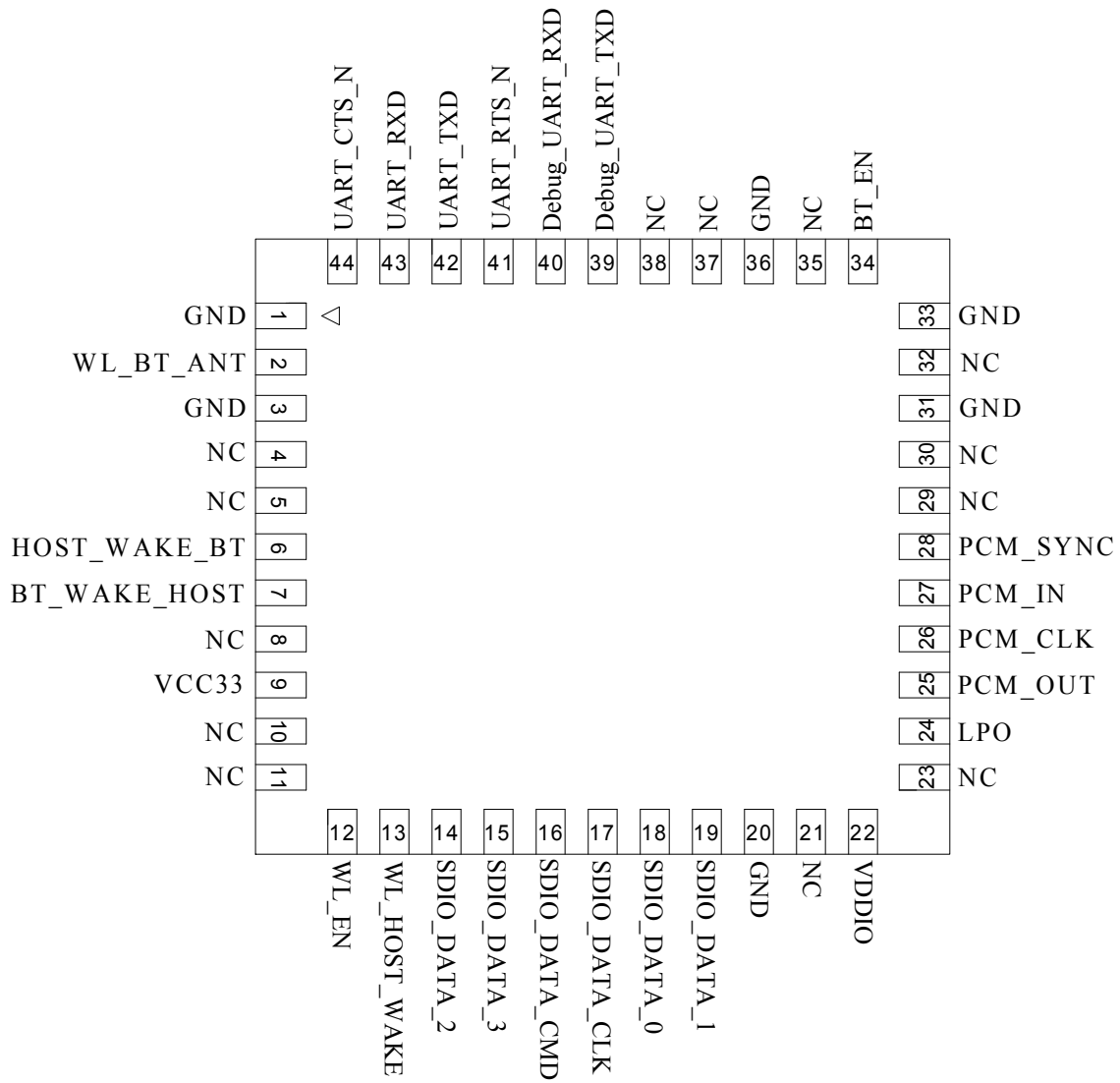
3.1 Bluetooth Specification

Feature	**Description**		
General Specification			
Bluetooth Standard	Bluetooth V5.0, BLE		
Host Interface	UART		
Antenna Reference	Small antennas with 0~2 dBi peak gain		
Frequency Band	2402 MHz ~ 2480 MHz		
Number of Channels	79 channels		
Modulation	GFSK, 8-DPSK, π/4-DQPSK		
RF Specification			
	Min.	**Typical.**	**Max.**
Output Power (Class 1)	2dBm	5 dBm	15dBm

Sensitivity @ BER=0.1% for GFSK (1Mbps)		-92 dBm	
Sensitivity @ BER=0.01% for π/4-DQPSK (2Mbps)		-92 dBm	
Sensitivity @ BER=0.01% for 8DPSK (3Mbps)		-85 dBm	
Maximum Input Level	GFSK (1Mbps):-20dBm		
	π/4-DQPSK (2Mbps) :-20dBm		
	8DPSK (3Mbps) :-20dBm		

4 Pin Assignments

4.1 Pin Outline



4.2 Pin Definition

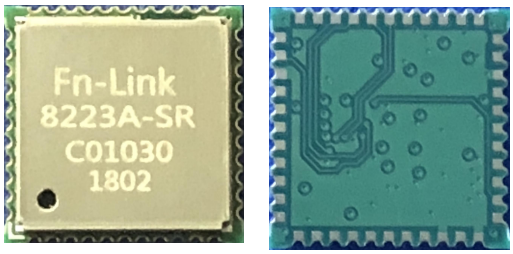
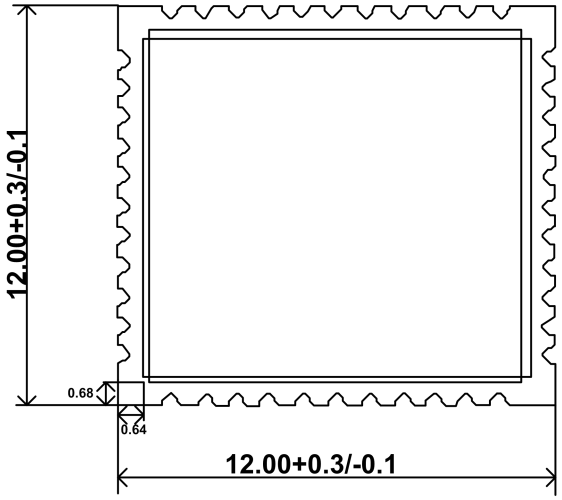
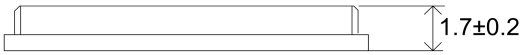
NO	Name	Type	Description	Voltage
1	GND	—	Ground connections	
2	WL_BT_ANT	I/O	RF I/O port	
3	GND	—	Ground connections	
4	NC	—	Floating (Don't connected to ground)	
5	NC	—	Floating (Don't connected to ground)	
6	HOST_WAKE_BT	I	HOST to wake-up Bluetooth device (IC pin55 :3D_FRAME_SYNC)	1.8V or 3.3V
7	BT_WAKE_HOST	O	Bluetooth device to wake-up HOST, Active high (IC pin93 :HCI_UART_WAKEHOST)	1.8V or 3.3V
8	NC	—	Floating (Don't connected to ground)	
9	VCC33	P	Main power voltage source input 3.3V	3.3V
10	NC	—	Floating (module pin is GND)	
11	NC	—	Floating (Don't connected to ground)	
12	WL_EN	I	Enable pin for WLAN device ON: pull high ; OFF: pull low	1.8V or 3.3V
13	WL_HOST_WAKE	O	WLAN to wake-up HOST (IC pin92:QOW)	1.8V or 3.3V
14	SDIO_DATA_2	I/O	SDIO data line 2, this pin must pull high 10KΩ resistor to VDDIO in main board.	1.8V or 3.3V
15	SDIO_DATA_3	I/O	SDIO data line 3	1.8V or 3.3V
16	SDIO_DATA_CMD	I/O	SDIO command line	1.8V or 3.3V
17	SDIO_DATA_CLK	I/O	SDIO clock line	1.8V or 3.3V
18	SDIO_DATA_0	I/O	SDIO data line 0	1.8V or 3.3V
19	SDIO_DATA_1	I/O	SDIO data line 1	1.8V or 3.3V
20	GND	—	Ground connections	1.8V or 3.3V
21	NC	—	Floating (Don't connected to ground) (IC pin48 :CLK_REQ)	
22	VDDIO	P	I/O Voltage supply input 1.8V or 3.3V	3.3V or 1.8V
23	NC	—	Floating (Don't connected to ground)	
24	LPO	I	External Low Power Clock input	1.8V or 3.3V

			(32.768KHz)	
25	PCM_OUT	O	PCM Data output	1.8V or 3.3V
26	PCM_CLK	I/O	PCM clock	1.8V or 3.3V
27	PCM_IN	I	PCM data input	1.8V or 3.3V
28	PCM_SYNC	I/O	PCM sync signal	1.8V or 3.3V
29	NC	—	Floating (Don't connected to ground)	
30	NC	—	Floating (Don't connected to ground)	
31	GND	—	Ground connections	
32	NC	—	Floating (Don't connected to ground)	
33	GND	—	Ground connections	
34	BT_EN	I	Enable pin for Bluetooth device ON: pull high ; OFF: pull low	1.8V or 3.3V
35	NC	—	Floating (Don't connected to ground)	
36	GND	—	Ground connections	
37	NC	—	Floating (Don't connected to ground)	
38	NC	—	Floating (Don't connected to ground)	
39	Debug_UART_TXD	O	Floating (Don't connected to ground) (IC pin61 :GPIO[19])	
40	Debug_UART_RXD	I	Floating (Don't connected to ground) (IC pin101 :GPIO[18])	
41	UART_RTS_N	O	Bluetooth UART interface	1.8V or 3.3V
42	UART_TXD	O	Bluetooth UART interface	1.8V or 3.3V
43	UART_RXD	I	Bluetooth UART interface	1.8V or 3.3V
44	UART_CTS_N	I	Bluetooth UART interface	1.8V or 3.3V

P:POWER I:INPUT O:OUTPUT

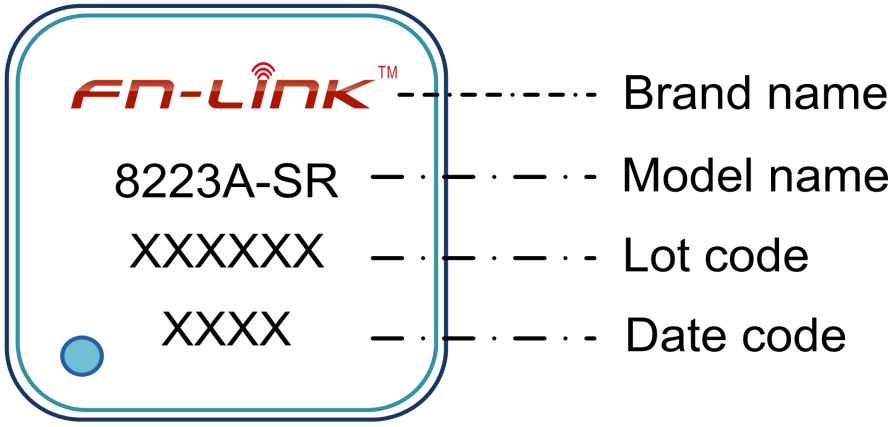
5 Dimensions

5.1 Module Picture

L x W : 12 x 12 (+0.3/-0.1) mm 	
H: 1.7 (±0.2) mm	
Weight	0.53g

5.2 Marking Description

< TOP VIEW >



Datecode：

XXXX ： -w2 model

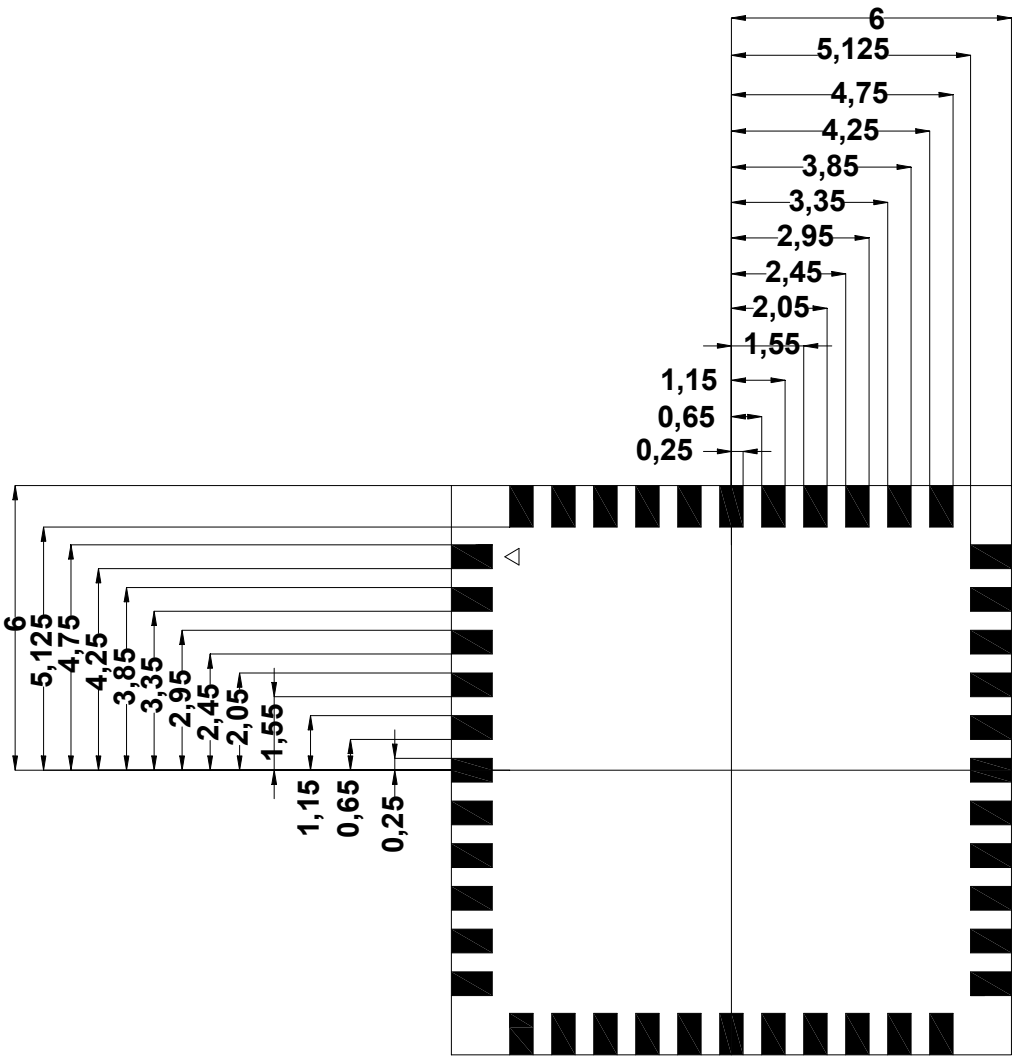
XXXXK2: -K2 model

XXXXW3: -W3 model

5.3 Module Physical Dimensions

(Unit: mm)

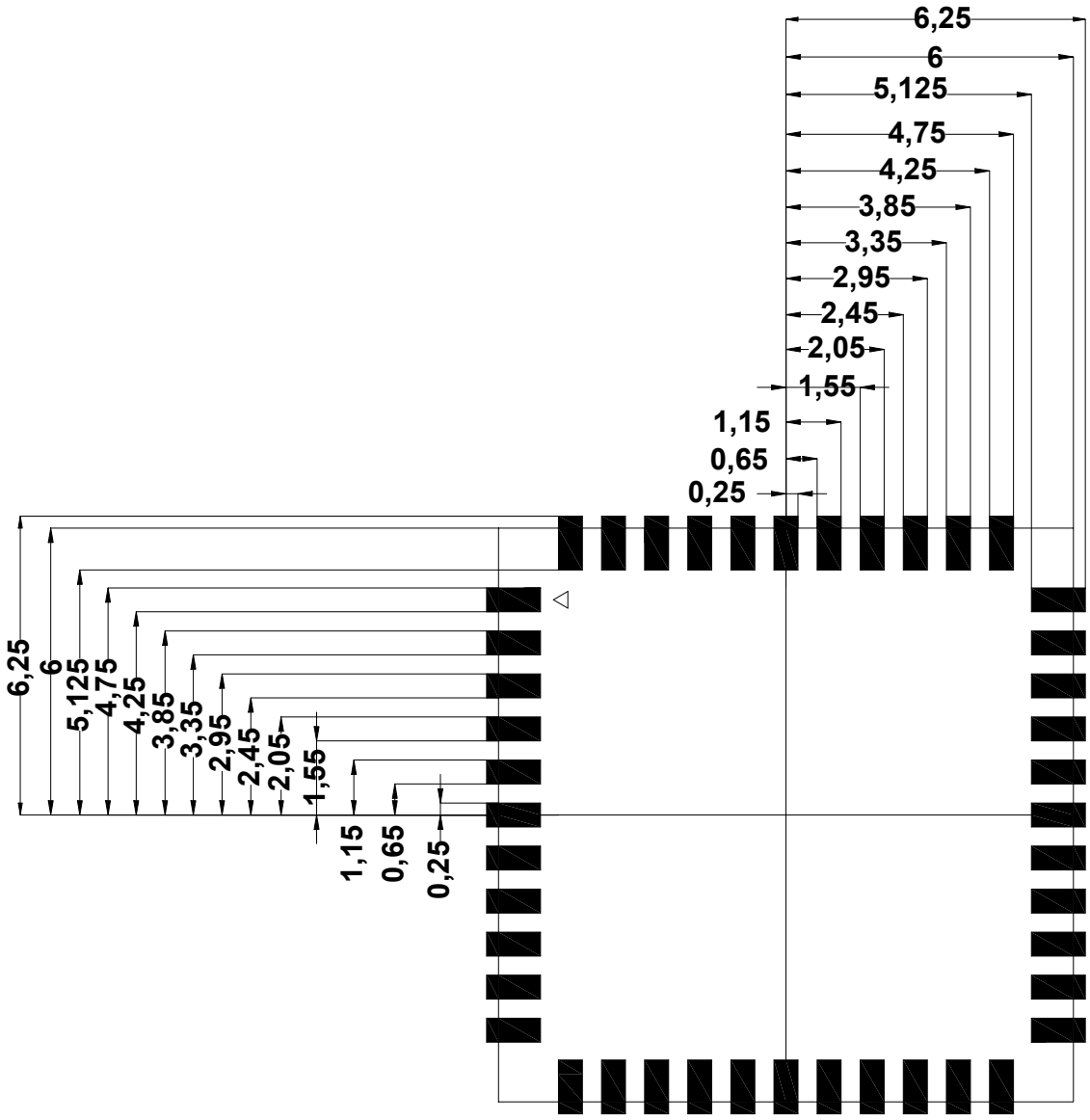
< TOP VIEW >



5.4 Layout Recommendation

(Unit: mm)

< TOP VIEW >


6,25
6
5,125
4,75
4,25
3,85
3,35
2,95
2,45
2,05
1,55
1,15
0,65
0,25

6 Host Interface Timing Diagram

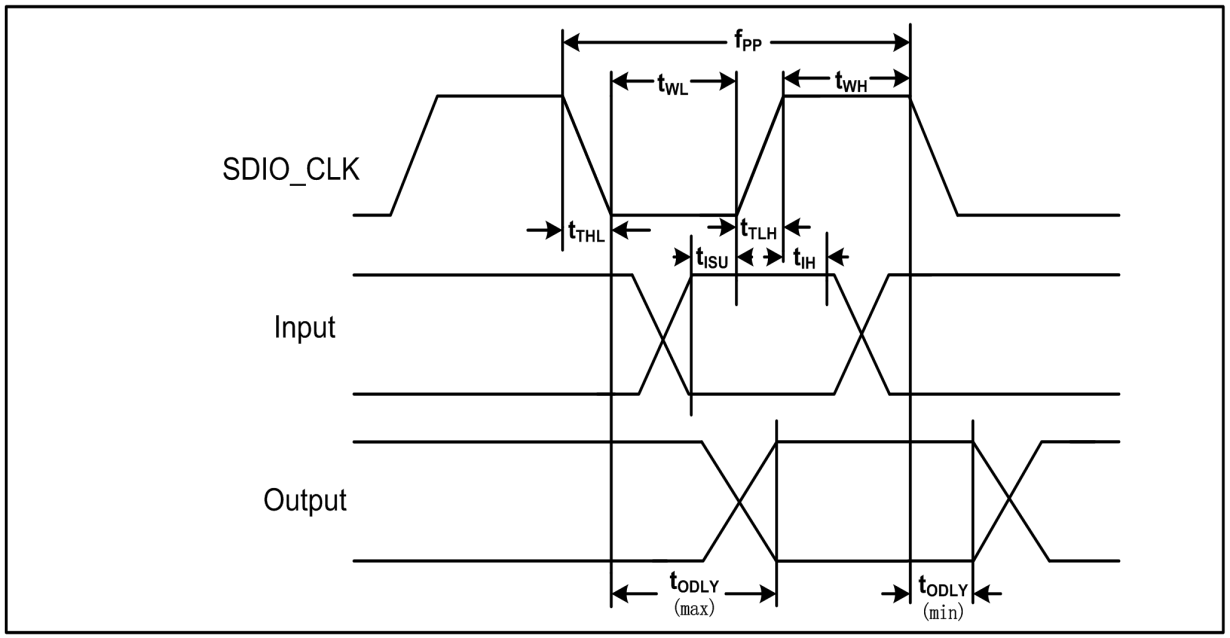
6.1 SDIO Pin Description

The module supports SDIO version 3.0 for all 1.8V 4-bit UHSI speeds: SDR50(100 Mbps), SDR104(208MHz) and DDR50(50MHz, dual rates) in addition to the 3.3V default speed(25MHz) and high speed (50 MHz). It has the ability to stop the SDIO clock and map the interrupt signal into a GPIO pin. This 'out-of-band' interrupt signal notifies the host when the WLAN device wants to turn on the SDIO interface. The ability to force the control of the gated clocks from within the WLAN chip is also provided.

SDIO Pin Description

SD 4-Bit Mode	
DATA0	Data Line 0
DATA1	Data Line 1 or Interrupt
DATA2	Data Line 2 or Read Wait
DATA3	Data Line 3
CLK	Clock
CMD	Command Line

6.2 SDIO Default Mode Timing Diagram

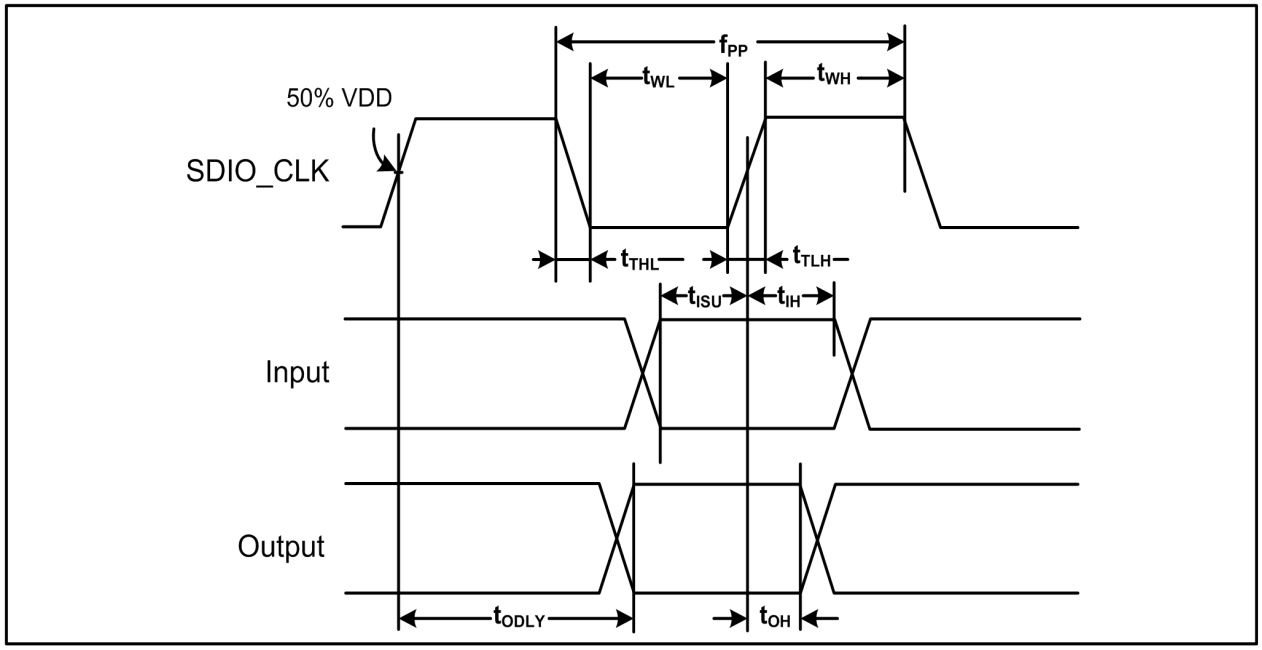


Parameter	*Symbol*	*Minimum*	*Typical*	*Maximum*	*Unit*
SDIO CLK(All values are referred to minimum VIH and maximum VIL[b])					
Frequency - Data Transfer mode	fPP	0	-	25	MHz
Frequency - Identification mode	fOD	0	-	400	kHz
Clock low time	tWL	10	-	-	ns
Clock high time	tWH	10	-	-	ns
Clock rise time	tTLH	-	-	10	ns
Clock low time	tTHL	-	-	10	ns
Inputs:CMD, DAT(referenced to CLK)					
Input setup time	tISU	5	-	-	ns
Input hold time	tIH	5	-	-	ns
Outputs:CMD, DAT(referenced to CLK)					
Output delay time - Data Transfer mode	tODLY	0	-	14	ns
Output delay time - Identification mode	tODLY	0	-	50	ns

a. Timing is based on CL ≤ 40 pF load on CMD and Data.

b. Min(Vih) = 0.7 × VDDIO and max(Vil) = 0.2 × VDDIO.

6.3 SDIO High Speed Mode Timing Diagram



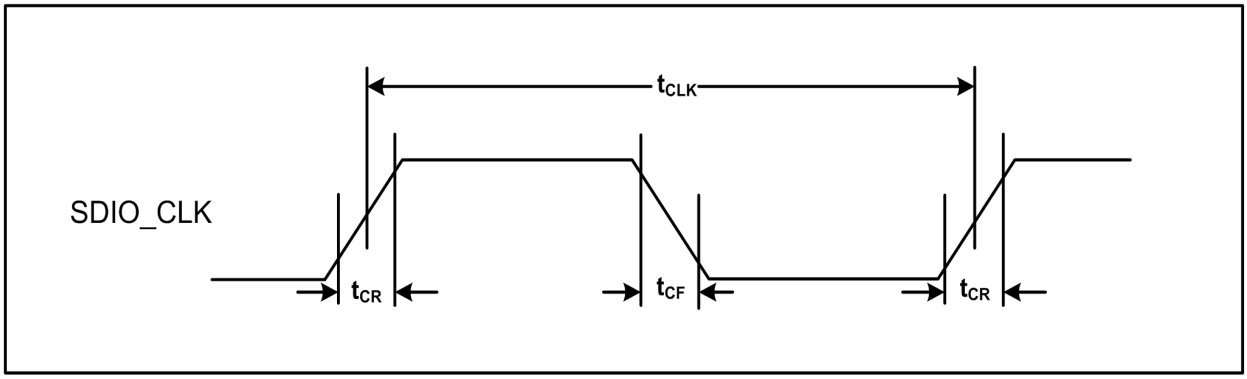
Parameter	*Symbol*	*Minimum*	*Typical*	*Maximum*	*Unit*
SDIO CLK(all values are referred to minimum VIH and maximum VIL[b])					
Frequency - Data Transfer mode	fPP	0	-	50	MHz
Frequency - Identification mode	fOD	0	-	400	kHz
Clock low time	tWL	7	-	-	ns
Clock high time	tWH	7	-	-	ns
Clock rise time	tTLH	-	-	3	ns
Clock low time	tTHL	-	-	3	ns
Inputs:CMD, DAT(referenced to CLK)					
Input setup time	tISU	6	-	-	ns
Input hold time	tIH	2	-	-	ns
Outputs:CMD, DAT(referenced to CLK)					
Output delay time - Data Transfer mode	tODLY	-	-	14	ns
Output delay time - Identification mode	tODLY	2.5	-	-	ns
Total system capacitance(each line)	CL	-	-	40	pF

a. Timing is based on CL ≤ 40 pF load on CMD and Data.

b. Min(Vih) = 0.7 × VDDIO and max(Vil) = 0.2 × VDDIO.

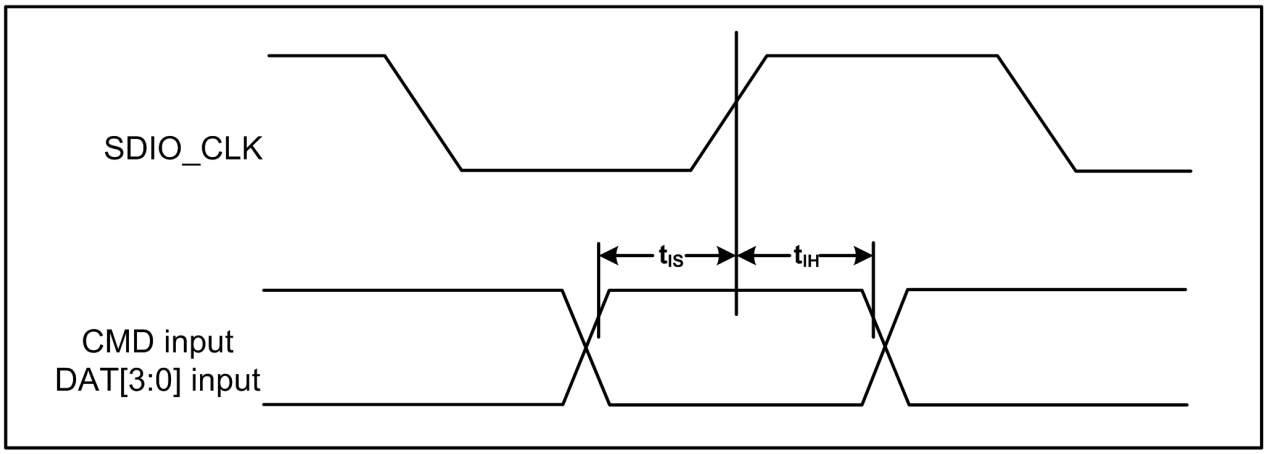
6.4 SDIO Bus Timing Specifications in SDR Modes

Clock timing(SDR Modes)



Parametwer	*Symbol*	*Minimum*	*Maximum*	*Unit*	*Comments*
-	t_{CLK}	40	-	ns	SDR12 mode
		20	-	ns	SDR25 mode
		10	-	ns	SDR50 mode
		4.8	-	ns	SDR104 mode
-	t_{CR}, t_{CF}	-	0.2 × t_{CLK}	ns	t_{CR}, t_{CF} < 2.00 ns (max)@100 MHz, C_{CARD} = 10 pF t_{CR}, t_{CF} < 0.96 ns (max)@208 MHz, C_{CARD} = 10 pF
Clock duty	-	30	70	%	-

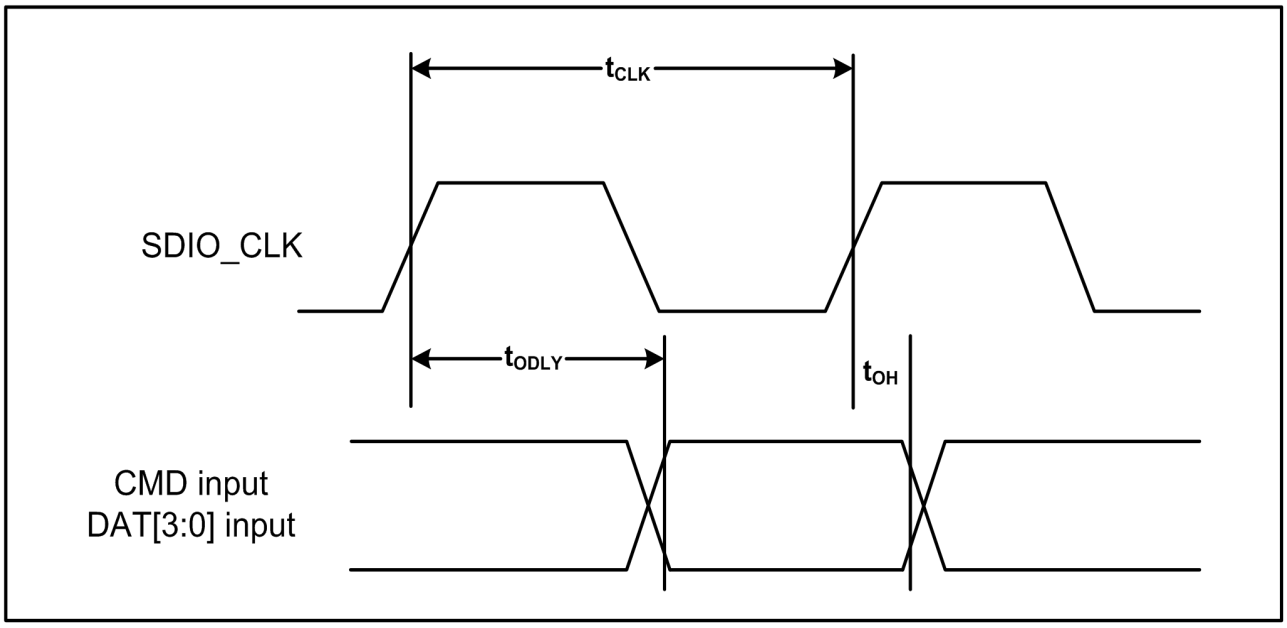
Card Input timing (SDR Modes)



Symbol	Minimum	Maximum	Unit	Comments
SDR104 Mode				
t_{IS}	1.70[a]	-	ns	C_{CARD} = 10pF, VCT = 0.975V
t_{IH}	0.80	-	ns	C_{CARD} = 5pF, VCT = 0.975V
SDR50 Mode				
t_{IS}	3.00	-	ns	C_{CARD} = 10pF, VCT = 0.975V
t_{IH}	0.80	-	ns	C_{CARD} = 5pF, VCT = 0.975V

a. SDIO 3.0 specification value is 1.40 ns.

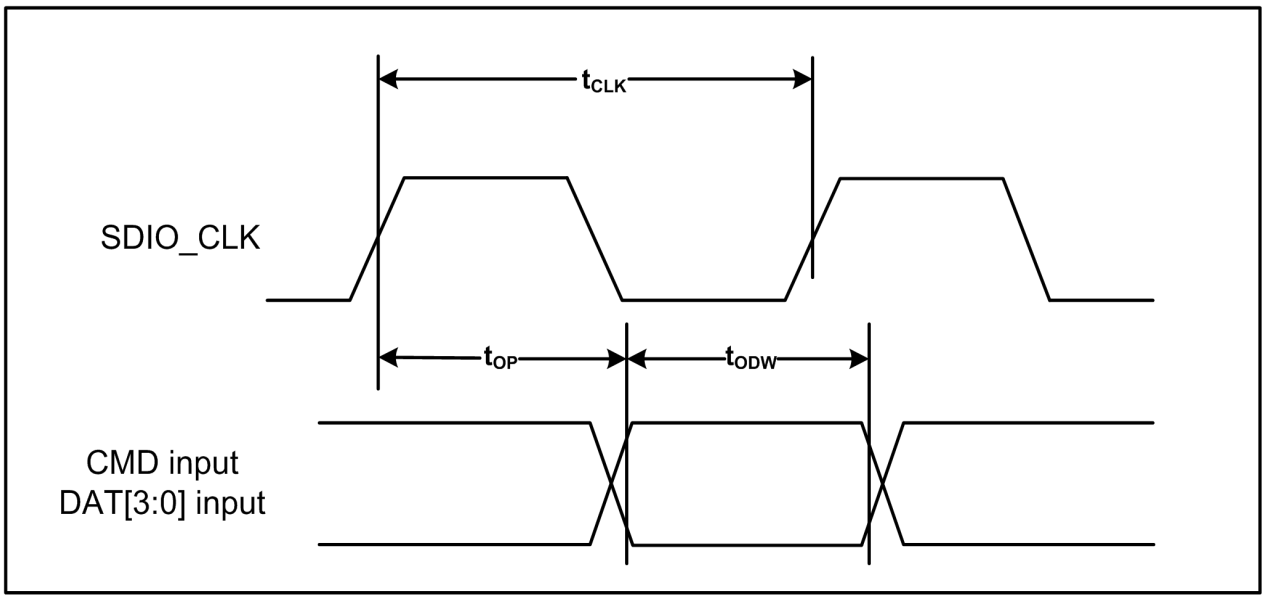
Card output timing (SDR Modes up to 100MHz)



Symbol	Minimum	Maximum	Unit	Comments
t_{ODLY}	-	7.85[a]	ns	t_{CLK}≥10 ns C_L=30 pF using driver type B for SDR50
t_{ODLY}	-	14.0	ns	t_{CLK}≥20 ns C_L=40 pF using for SDR12, SDR25
t_{OH}	1.5	-	ns	Hold time at the t_{ODLY}(min) CL=15 pF

a. SDIO 3.0 specification value is 7.5 ns.

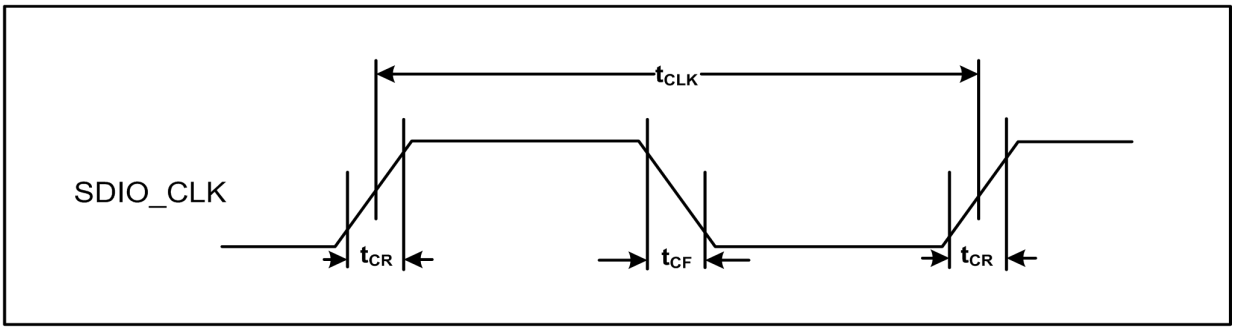
Card output timing (SDR Modes 100MHz to 208MHz)



Symbol	*Minimum*	*Maximum*	*Unit*	*Comments*
t_{OP}	0	2	UI	Card output phase
$\triangle t_{OP}$	-350	+1550	ps	Delay variation due to temp change after tuning
t_{ODW}	0.6	-	UI	t_{ODW} = 2.88 ns @ 208 MHz

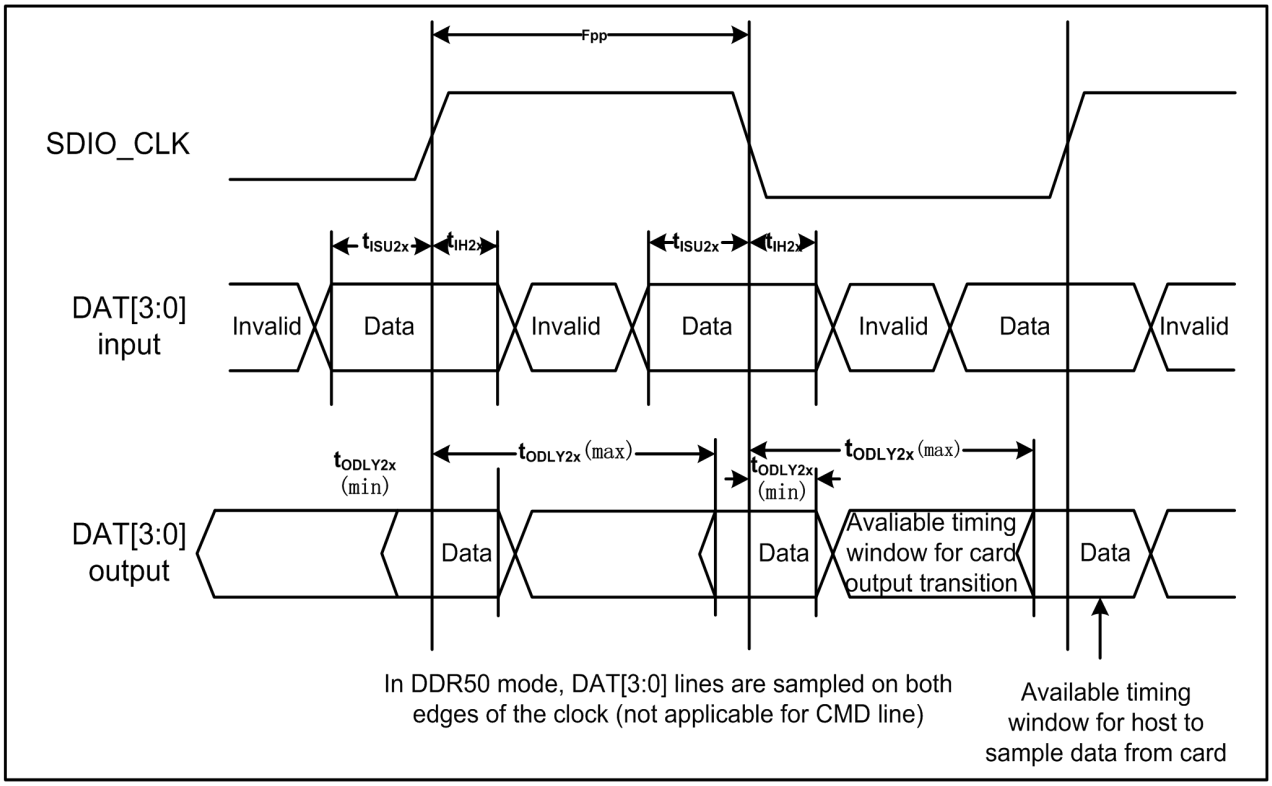
- $\triangle t_{OP}$ = +1550 ps for junction temperature of $\triangle t_{OP}$ = 90 degrees during operation
- $\triangle t_{OP}$ = -350 ps for junction temperature of $\triangle t_{OP}$ = -20 degrees during operation
- $\triangle t_{OP}$ = +2600 ps for junction temperature of $\triangle t_{OP}$ = -20 to +125 degrees during operation

6.5 SDIO Bus Timing Specifications in DDR50 Mode



parameter	*Symbol*	*Minimum*	*Maximum*	*Unit*	*Comments*
-	t_{CLK}	20	-	ns	DDR50 mode
-	t_{CR}, t_C	-	0.2 ×t_{CLK}	ns	t_{CR}, t_{CF} < 4.00 ns (max)@50 MHz, C_{CARD} = 10 pF
Clock duty	-	45	55	%	-

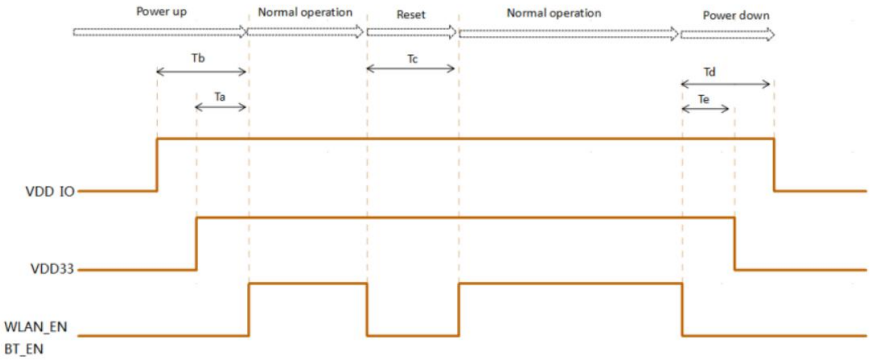
Data Timing



parameter	*Symbol*	*Minimum*	*Maximum*	*Unit*	*Comments*
Input CMD					
Input setup time	t_{ISU}	6	-	ns	C_{CARD} < 10 pF (1 Card)
Input hold time	t_{IH}	0.8	-	ns	C_{CARD} < 10 pF (1 Card)
Output CMD					
Output delay time	t_{ODLY}	-	13.7	ns	C_{CARD} < 30 pF (1 Card)
Output hold time	t_{OH}	1.5	-	ns	C_{CARD} < 15 pF (1 Card)
Input DAT					
Input setup time	t_{ISU2x}	3	-	ns	C_{CARD} < 10 pF (1 Card)
Input hold time	t_{IH2x}	0.8	-	ns	C_{CARD} < 10 pF (1 Card)
Output CMD					
Output delay time	t_{ODLY2x}	-	7.85[a]	ns	C_{CARD} < 25 pF (1 Card)
Output hold time	t_{ODLY2x}	1.5	-	ns	C_{CARD} < 15 pF (1 Card)

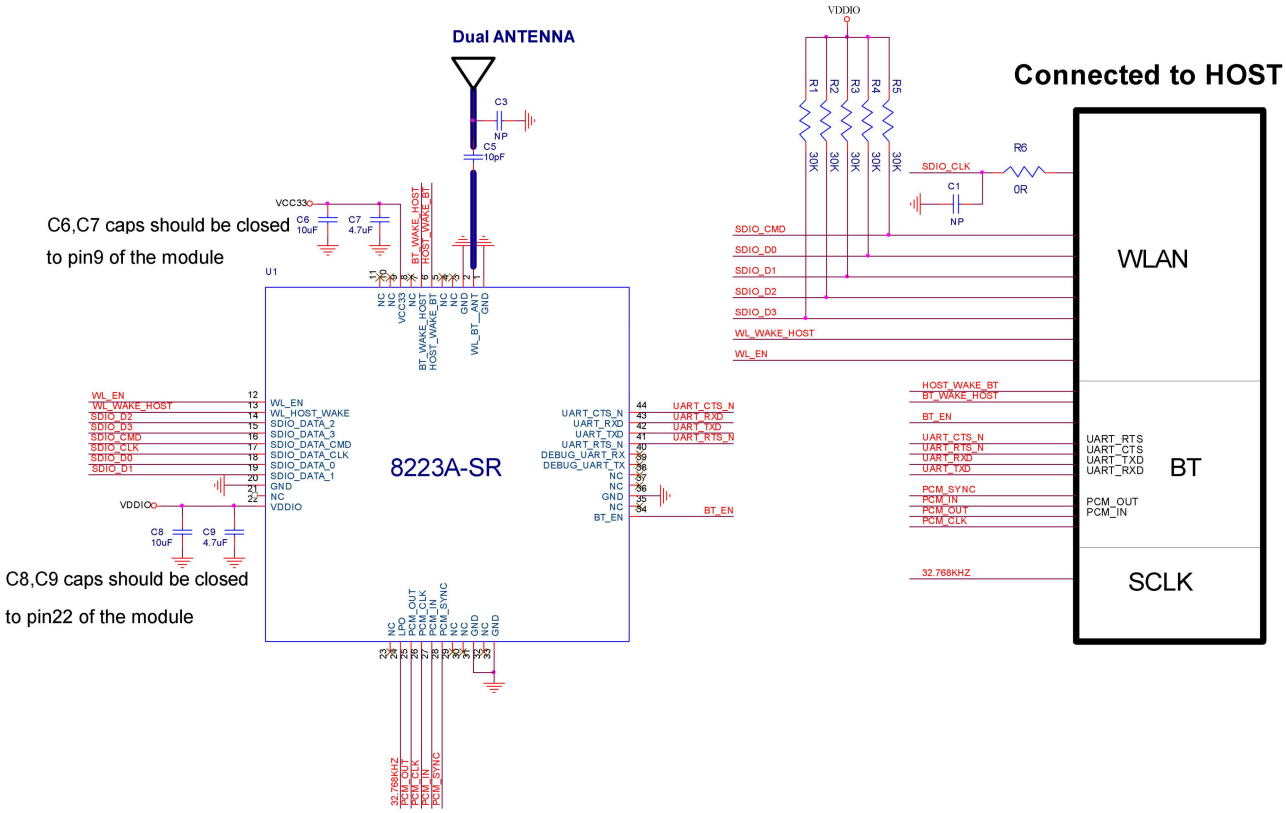
a. SDIO 3.0 specification value is 7.0 ns

7 Power timing requirements



Symbol	Description	Min	Max	Unit
Ta	External 3.3V to chip enable	5	-	us
Tb	VDD_IO valid to chip enable	10	-	us
Tc	Minimum reset pulse length	10	-	ms
Td	chip disable to VDD33 powerdonw	TBD	-	us
Te	Chip disable to VDD_IO powerdonw	TBD	-	us

8 Reference Design



9 Ordering Information

Part No.	Description
FG1023SM13-W2	QCA1023-0/QCA9377-3, a/b/g/n/ac Wi-Fi+BLE5.0, 1T1R, 12X12mm SDIO+Uart, V1.0
FG1023SM13-K2	QCA1023-0/QCA9377-3, a/b/g/n/ac Wi-Fi+BLE5.0, 1T1R, 12X12mm SDIO+Uart, V1.0(客供 IC)
PA1023SM13-W3	QCA1023-0/QCA9377-3, a/b/g/n/ac Wi-Fi+BLE5.0, 1T1R, 12X12mm SDIO+Uart, V1.0(GXX 版)

10 The Key Material List

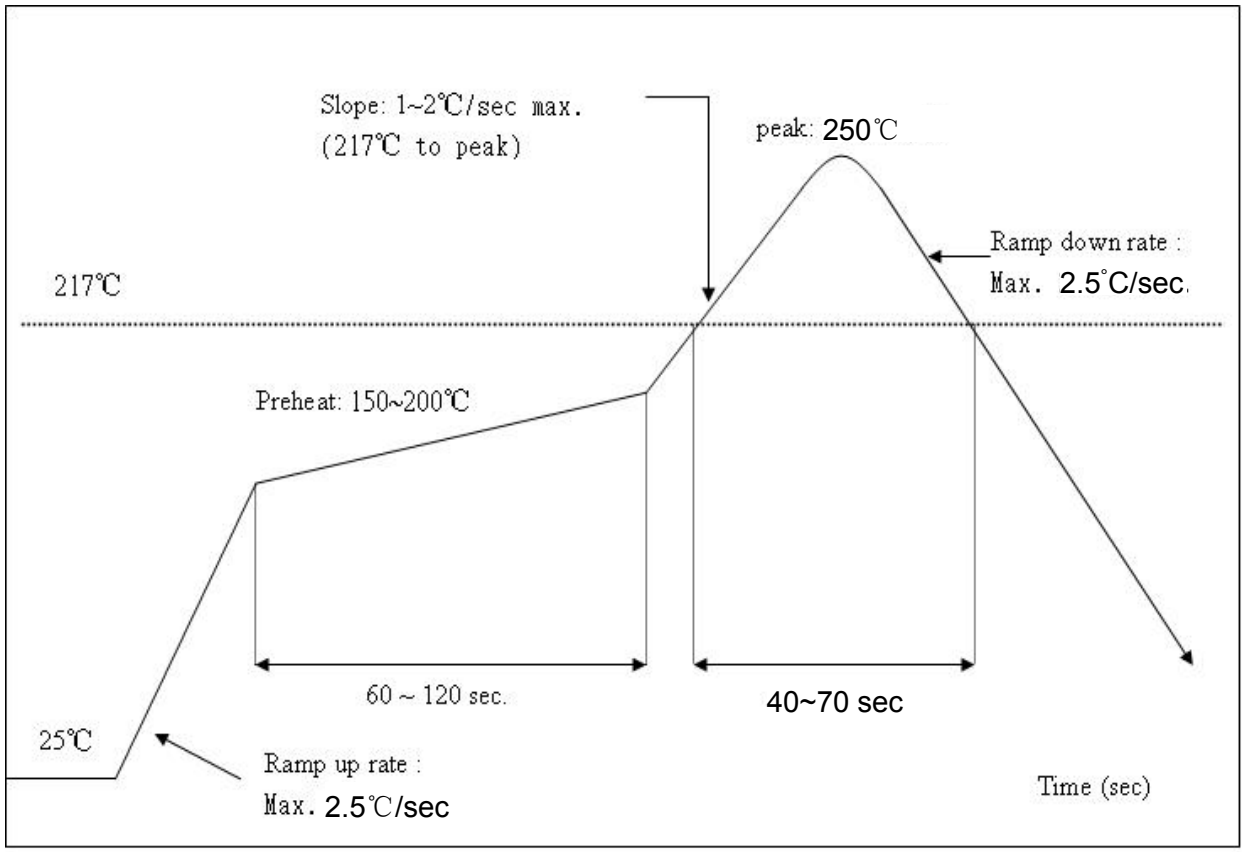
Inductor	2016 1.5uH, ±20%，800mA	Microgate,Cenke,Ceaiya,sunlord
Crystal	2016 48MHZ 10ppm, 8.8pF	Hosonic,ECEC,TKD,JWT,TST,SIWARD
Diplexer	Diplexer,1608,2.4G+5G	ACX,Wlsain,Glead,maglayers
Chipset	QCA1023-0/QCA9377-3	Qualcomm
Shielding cover	F1023XM13-W1 Shielding cover	精力通，信太
PCB	8223A-SR-V1.0Green,6L,12X12X0.498mm	Sunlord,Brainpower PCB,KX-PCB

11 Recommended Reflow Profile

Referred to IPC/JEDEC standard.

Peak Temperature : <250°C

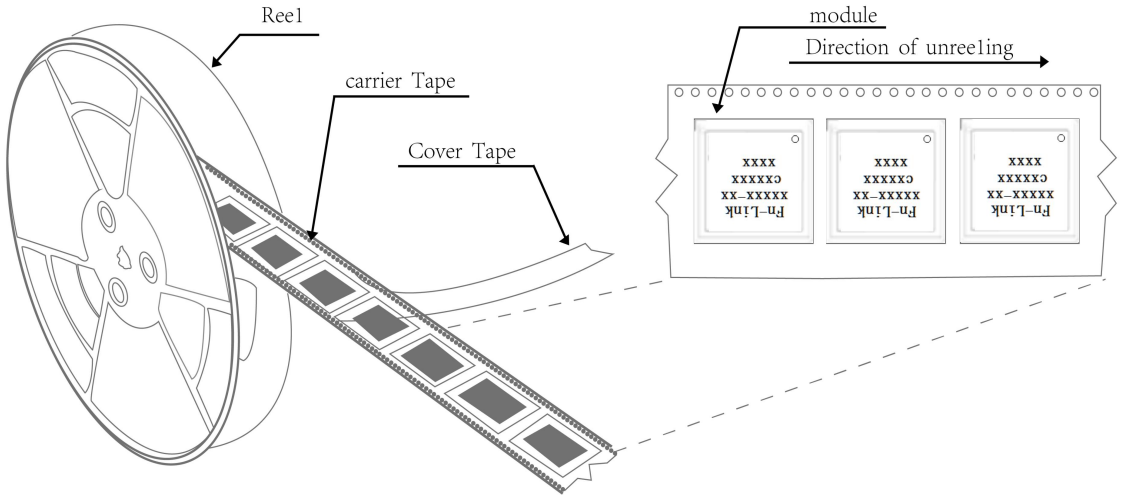
Number of Times : ≤2 times



12 Packing Information

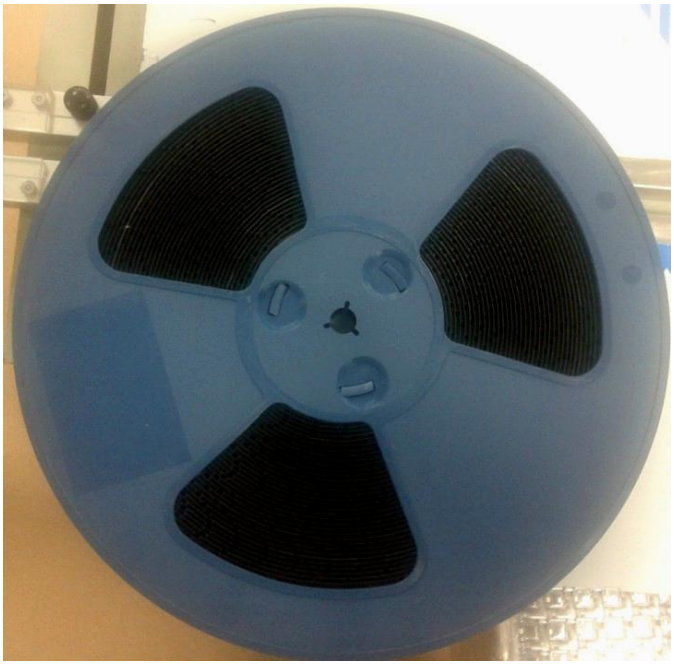
12.1 Reel

A roll of 1500pcs



12.2 Packaging Detail

Tape and Reel Package



Using self-adhesive tape

Size of black tape: 24mm*32.6m the cover tape: 2.13mmm*32.6m

Color of plastic disc: blue

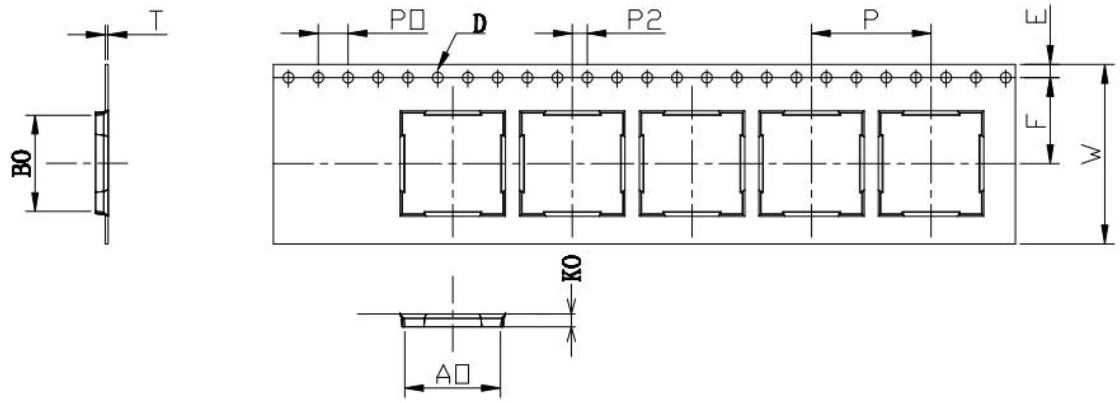
NY bag size:460mm*385mm

size ： 350*350*35mm

The packing case size:350*210*370mm

12.3 Carrier Tape Detail

ITEM	W	A0	B0	D	F	E	K0	P0	P2	P	T
DIM	24	12.45	12.45	1.50	11.5	1.75	2.60	4.0	2.0	16.0	0.30
TOLE	+0.3 -0.3	±0.10	±0.10	+0.1 -0.0	+0.1 -0.1	±0.1	±0.10	±0.1	±0.1	±0.1	±0.05



12.4 Moisture sensitivity

The Modules is a Moisture Sensitive Device level 3, in according with standard IPC/JEDEC J-STD-020, take care
all the relatives requirements for using this kind of components.
Moreover, the customer has to take care of the following conditions:
a) Calculated shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH)
b) Environmental condition during the production: 30°C / 60% RH according to IPC/JEDEC J-STD-033A paragraph 5
c) The maximum time between the opening of the sealed bag and the reflow process must be 168 hours if condition
b) “IPC/JEDEC J-STD-033A paragraph 5.2” is respected
d) Baking is required if conditions b) or c) are not respected
e) Baking is required if the humidity indicator inside the bag indicates 10% RH or more